



Use of microcutting for high throughput electrode patterning on a flexible substrate

Citation

Janka, M., Tuukkanen, S., Tuorila, H., Viheriälä, J., Honkanen, M., Stingelin, N., & Lupo, D. (2014). Use of microcutting for high throughput electrode patterning on a flexible substrate. *Journal of Micromechanics and Microengineering*, 24(1), [015015]. <https://doi.org/10.1088/0960-1317/24/1/015015>

Year

2014

Version

Peer reviewed version (post-print)

Link to publication

[TUTCRIS Portal \(http://www.tut.fi/tutcris\)](http://www.tut.fi/tutcris)

Published in

Journal of Micromechanics and Microengineering

DOI

[10.1088/0960-1317/24/1/015015](https://doi.org/10.1088/0960-1317/24/1/015015)

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Supplementary material

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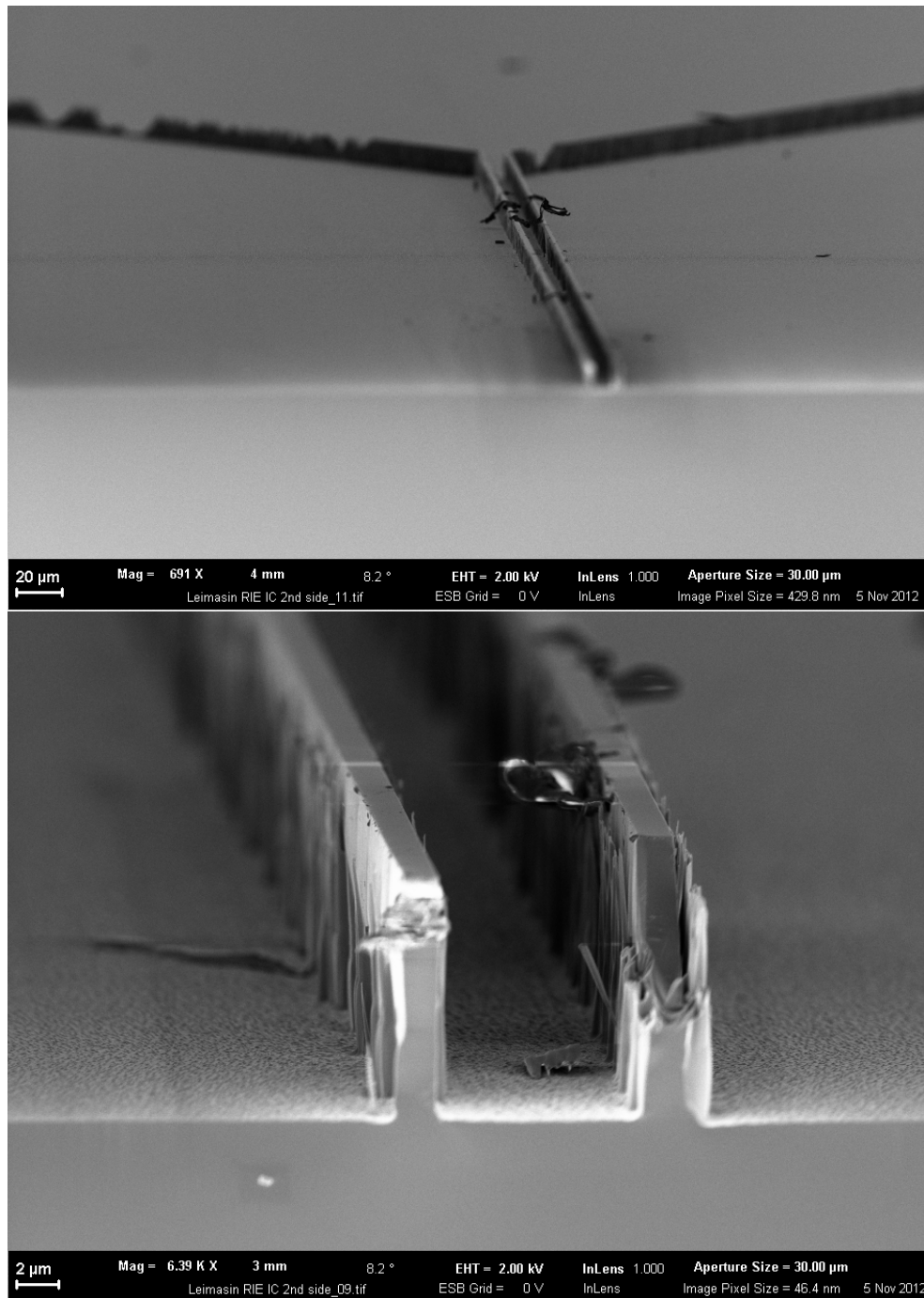


Figure 1: SEM images of stamp 2 (two different magnifications).

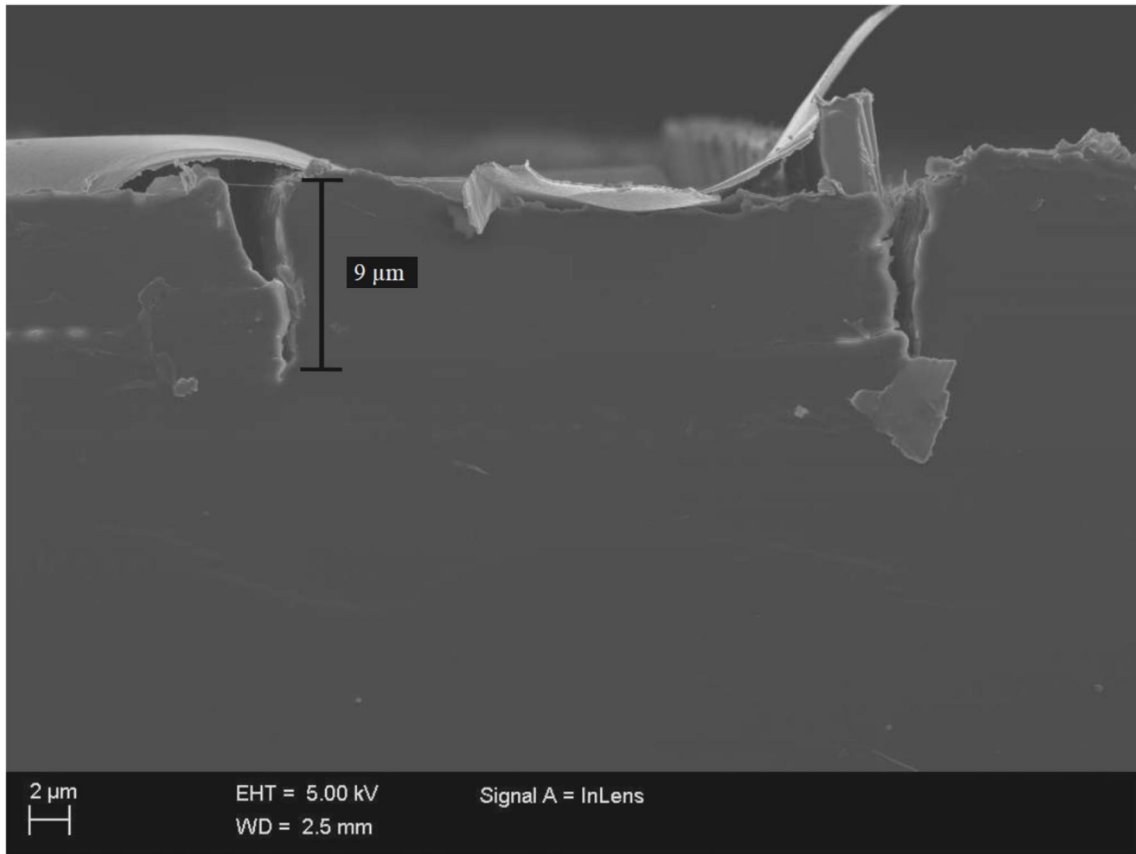


Figure 2: SEM image of the cross-section profile of microcut sample using NIL-tool and stamp 2.

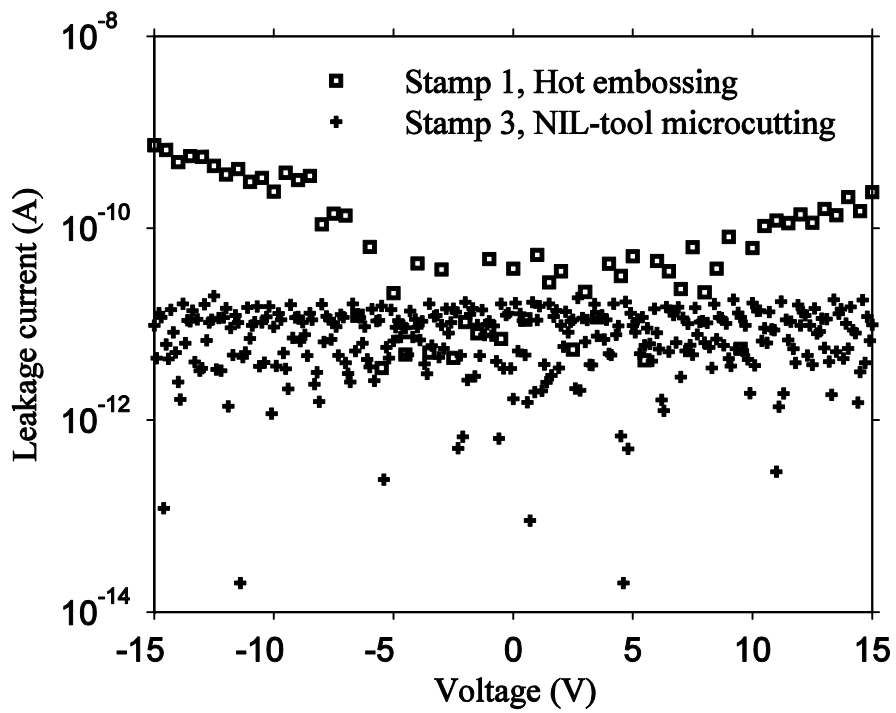


Figure 3: Leakage currents between the adjacent electrodes patterned by hot embossing with stamp 1 and NIL-tool microcutting with stamp 3.